

WAFER SAW

MANUFACTURER : Disco

MODEL : DAD3350

Samples

- Samples size : up to 200 mm (8 in.)
- Thickness: 10 mm maximum
- Cutting depth: 7 mm maximum

Characteristics

- Cutting area : 260 mm X 260 mm
- Vertical displacement range : 31 mm
- Positioning precision : 3 μm
- Lateral precision : 2 μm
- Vertical displacement precision : 0,05 μm
- Vertical repeatability : 1 μm
- Blade rotating speed : from 3 000 to 30 000 rpm
- Cutting speed : 600 mm/s with feedback control
- Angle of rotation : 360° with feedback control

MATERIALS

- Glass
- Quartz
- Ceramics
- Silicon
- GaAs